

LISTING OF CLAIMS:

1. (Currently amended) A multi-layer printed circuit board comprising:

a resin substrate including a plurality of laminated thermoplastic resin films;

a thin film resistor embedded in the resin substrate; and

an electrode disposed on the thin film resistor,

wherein the thermoplastic resin film includes a conductive pattern made of metallic film, and

wherein the conductive pattern is disposed over or under the electrode, the conductive pattern is disposed nearer to the electrode than any other conductive pattern over or under the electrode, and the conductive pattern covers all of a periphery of the electrode,

wherein all of a periphery of the thin film resistor is covered with the conductive pattern disposed over or under the resistor.

2. (Canceled)

3. (Original) The multi-layer printed circuit board according to claim 1,

wherein the thin film resistor is covered with the conductive pattern disposed on a side opposite to the electrode across the thin film resistor.

4. (Original) The multi-layer printed circuit board

according to claim 1,

wherein the thin film resistor has a thickness equal to or thinner than $10\mu\text{m}$.

5. (Original) The multi-layer printed circuit board according to claim 4,

wherein the thin film resistor has the thickness equal to or thinner than $1\mu\text{m}$.

6. (Original) The multi-layer printed circuit board according to claim 1,

wherein the resin substrate includes a plurality of thermoplastic resin films laminated and bonded together.

7. (Original) The multi-layer printed circuit board according to claim 1,

wherein the conductive pattern prevents a fluidized thermoplastic resin from moving toward the thin film resistor when a thermoplastic resin composing the thermoplastic resin film is fluidized.

8. (Previously presented) A multi-layer printed circuit board comprising:

a resin substrate including a plurality of laminated thermoplastic resin films; and

a thin film resistor embedded in the resin substrate,

wherein the thermoplastic resin film includes a conductive pattern, which is disposed on a surface of the resin film and

made of metallic film,

wherein the resin substrate includes a hole filled with a conductive material,

wherein the thin film resistor is directly connected to the conductive pattern through the conductive material in the hole, the conductive pattern being disposed over or under the resistor, the conductive pattern being disposed nearer to the thin film resistor than any other conductive pattern over or under the resistor, and

wherein all of a periphery of the thin film resistor is covered with the conductive pattern.

9. (Original) The multi-layer printed circuit board according to claim 8,

wherein the thin film resistor is covered with the conductive pattern disposed over or under the resistor.

10. (Original) The multi-layer printed circuit board according to claim 8,

wherein the thin film resistor has a thickness equal to or thinner than $10\mu\text{m}$.

11. (Original) The multi-layer printed circuit board according to claim 10,

wherein the thin film resistor has the thickness equal to or thinner than $1\mu\text{m}$.

12. (Original) The multi-layer printed circuit board

according to claim 8,

wherein the resin substrate includes a plurality of thermoplastic resin films laminated and bonded together.

13. (Original) The multi-layer printed circuit board according to claim 8,

wherein the conductive pattern prevents a fluidized thermoplastic resin from moving toward the thin film resistor when a thermoplastic resin composing the thermoplastic resin film is fluidized.

Claims 14-21 (Canceled)

22. (New) A multi-layer printed circuit board comprising:
a resin substrate including a plurality of laminated thermoplastic resin films;

a thin film resistor embedded in the resin substrate; and
an electrode disposed on the thin film resistor,

wherein the thermoplastic resin film includes a conductive pattern made of metallic film, and

wherein the conductive pattern is disposed over or under the electrode, the conductive pattern is disposed nearer to the electrode than any other conductive pattern over or under the electrode, and the conductive pattern covers all of a periphery of the electrode;

wherein the thin film resistor is covered with the conductive pattern disposed on a side opposite to the electrode

across the thin film resistor.

23. (New) A multi-layer printed circuit board comprising:
 - a resin substrate including a plurality of laminated thermoplastic resin films;
 - a thin film resistor embedded in the resin substrate; and
 - an electrode disposed on the thin film resistor,
wherein the thermoplastic resin film includes a conductive pattern made of metallic film, and
wherein the conductive pattern is disposed over or under the electrode, the conductive pattern is disposed nearer to the electrode than any other conductive pattern over or under the electrode, and the conductive pattern covers all of a periphery of the electrode;
 - wherein the conductive pattern prevents a fluidized thermoplastic resin from moving toward the thin film resistor when a thermoplastic resin composing the thermoplastic resin film is fluidized.